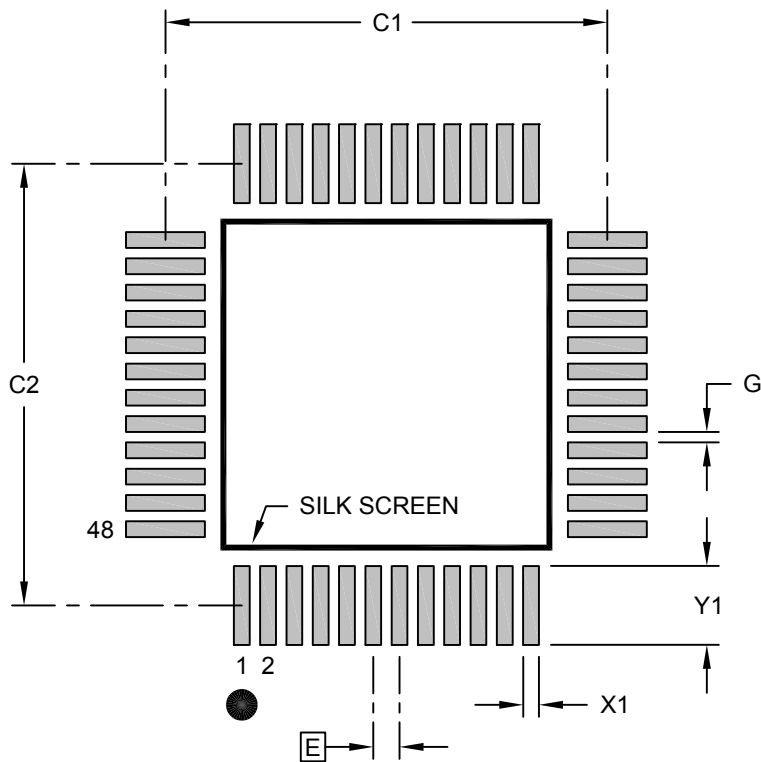


# 48-Lead Plastic Thin Quad Flatpack (PT) - 7x7x1.0 mm Body [TQFP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



## RECOMMENDED LAND PATTERN

| Units                    |    | MILLIMETERS |      |      |
|--------------------------|----|-------------|------|------|
| Dimension Limits         |    | MIN         | NOM  | MAX  |
| Contact Pitch            | E  | 0.50 BSC    |      |      |
| Contact Pad Spacing      | C1 |             | 8.40 |      |
| Contact Pad Spacing      | C2 |             | 8.40 |      |
| Contact Pad Width (X48)  | X1 |             |      | 0.30 |
| Contact Pad Length (X48) | Y1 |             |      | 1.50 |
| Distance Between Pads    | G  | 0.20        |      |      |

### Notes:

1. Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process